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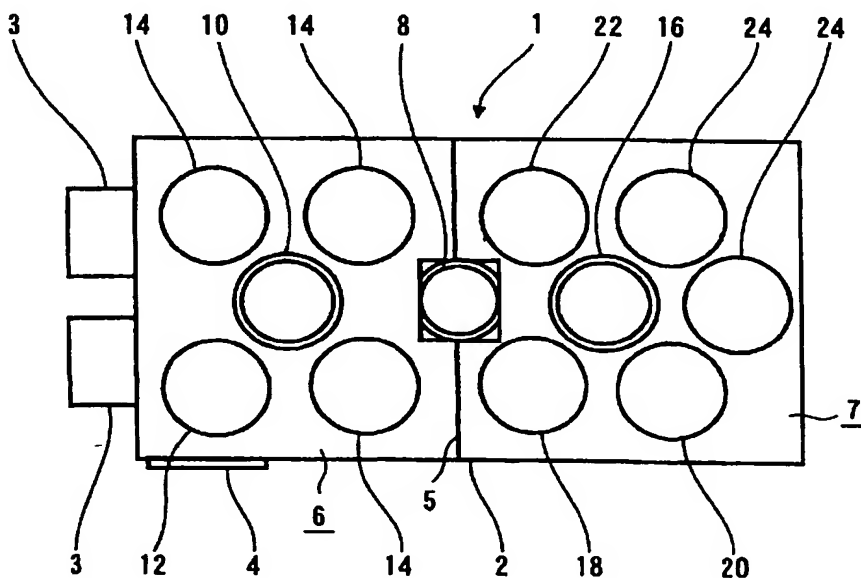
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(54) Title: PLATING METHOD AND APPARATUS



(57) Abstract: A plating method comprising applying an ultraviolet ray to a surface of a substrate or exposing a surface of a substrate to an ozone gas or bringing a surface of a substrate into contact with ozone water or bringing a surface of a substrate into contact with electrolytic ionized water or performing a team treatment using steam on a surface of a substrate, and plating the surface of the substrate after said applying, exposing, bringing or performing process. A plating method comprising performing a team treatment using steam on a surface of a substrate, and performing a wet process on the surface of the substrate of a substrate with an acidic plating solution, cleaning the surface of the substrate with pure water and cleaning the surface of the substrate with an alkaline aqueous solution. A plating apparatus adapted to perform at least one of said methods.

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